

| Parameter                                      | Symbol     | Conditions                                   | Values |      |      | Unit |
|------------------------------------------------|------------|----------------------------------------------|--------|------|------|------|
|                                                |            |                                              | min.   | typ. | max. |      |
| Thermal characteristics <sup>2)</sup>          |            |                                              |        |      |      |      |
| Thermal resistance, junction - case            | $R_{thJC}$ |                                              | -      | -    | 0.8  | K/W  |
| Thermal resistance, junction - ambient, leaded | $R_{thJA}$ |                                              | -      | -    | 62   |      |
| SMD version, device on PCB                     | $R_{thJA}$ | minimal footprint                            | -      | -    | 62   |      |
|                                                |            | 6 cm <sup>2</sup> cooling area <sup>3)</sup> | -      | -    | 40   |      |

**Electrical characteristics**, at  $T_j=25\text{ }^{\circ}\text{C}$ , unless otherwise specified

#### Static characteristics

|                                  |               |                                                                               |     |     |     |               |
|----------------------------------|---------------|-------------------------------------------------------------------------------|-----|-----|-----|---------------|
| Drain-source breakdown voltage   | $V_{(BR)DSS}$ | $V_{GS}=0\text{ V}, I_D=1\text{ mA}$                                          | 40  | -   | -   | V             |
| Gate threshold voltage           | $V_{GS(th)}$  | $V_{DS}=V_{GS}, I_D=120\text{ }\mu\text{A}$                                   | 2.1 | 3.0 | 4.0 |               |
| Zero gate voltage drain current  | $I_{DSS}$     | $V_{DS}=40\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ }^{\circ}\text{C}$       | -   | -   | 1   | $\mu\text{A}$ |
|                                  |               | $V_{DS}=40\text{ V}, V_{GS}=0\text{ V}, T_j=125\text{ }^{\circ}\text{C}^{2)}$ | -   | -   | 100 |               |
| Gate-source leakage current      | $I_{GSS}$     | $V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$                                       | -   | -   | 100 | nA            |
| Drain-source on-state resistance | $R_{DS(on)}$  | $V_{GS}=10\text{ V}, I_D=80\text{ A}$                                         | -   | 2.8 | 3.5 | m $\Omega$    |
|                                  |               | $V_{GS}=10\text{ V}, I_D=80\text{ A},$<br>SMD version                         | -   | 2.5 | 3.2 |               |

| Parameter | Symbol | Conditions | Values |      |      | Unit |
|-----------|--------|------------|--------|------|------|------|
|           |        |            | min.   | typ. | max. |      |

### Dynamic characteristics<sup>2)</sup>

|                              |              |                                                                                 |   |      |      |    |
|------------------------------|--------------|---------------------------------------------------------------------------------|---|------|------|----|
| Input capacitance            | $C_{iss}$    | $V_{GS}=0\text{ V}, V_{DS}=25\text{ V},$<br>$f=1\text{ MHz}$                    | - | 5600 | 7300 | pF |
| Output capacitance           | $C_{oss}$    |                                                                                 | - | 1540 | 2000 |    |
| Reverse transfer capacitance | $C_{rss}$    |                                                                                 | - | 240  | 350  |    |
| Turn-on delay time           | $t_{d(on)}$  | $V_{DD}=20\text{ V}, V_{GS}=10\text{ V},$<br>$I_D=80\text{ A}, R_G=3.5\ \Omega$ | - | 25   | -    | ns |
| Rise time                    | $t_r$        |                                                                                 | - | 17   | -    |    |
| Turn-off delay time          | $t_{d(off)}$ |                                                                                 | - | 39   | -    |    |
| Fall time                    | $t_f$        |                                                                                 | - | 14   | -    |    |

### Gate Charge Characteristics<sup>2)</sup>

|                       |               |                                                                            |   |     |     |    |
|-----------------------|---------------|----------------------------------------------------------------------------|---|-----|-----|----|
| Gate to source charge | $Q_{gs}$      | $V_{DD}=32\text{ V}, I_D=80\text{ A},$<br>$V_{GS}=0\text{ to }10\text{ V}$ | - | 30  | 40  | nC |
| Gate to drain charge  | $Q_{gd}$      |                                                                            | - | 20  | 35  |    |
| Gate charge total     | $Q_g$         |                                                                            | - | 83  | 110 |    |
| Gate plateau voltage  | $V_{plateau}$ |                                                                            | - | 5.4 | -   | V  |

### Reverse Diode

|                                                |               |                                                                   |   |    |     |    |
|------------------------------------------------|---------------|-------------------------------------------------------------------|---|----|-----|----|
| Diode continuous forward current <sup>2)</sup> | $I_S$         | $T_C=25\text{ °C}$                                                | - | -  | 80  | A  |
| Diode pulse current <sup>2)</sup>              | $I_{S,pulse}$ |                                                                   | - | -  | 320 |    |
| Diode forward voltage                          | $V_{SD}$      | $V_{GS}=0\text{ V}, I_F=80\text{ A},$<br>$T_j=25\text{ °C}$       | - | 1  | 1.3 | V  |
| Reverse recovery time <sup>2)</sup>            | $t_{rr}$      | $V_R=20\text{ V}, I_F=I_S,$<br>$di_F/dt=100\text{ A}/\mu\text{s}$ | - | 46 | -   | ns |
| Reverse recovery charge <sup>2)</sup>          | $Q_{rr}$      |                                                                   | - | 73 | -   | nC |

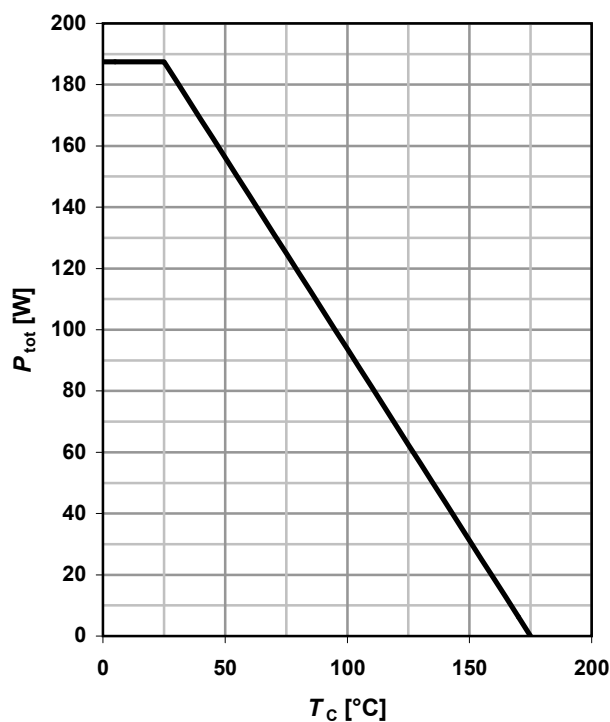
<sup>1)</sup> Current is limited by bondwire; with an  $R_{thJC} = 0.8\text{K/W}$  the chip is able to carry 182A at 25°C. For detailed information see Application Note ANPS071E at [www.infineon.com/optimos](http://www.infineon.com/optimos)

<sup>2)</sup> Defined by design. Not subject to production test.

<sup>3)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

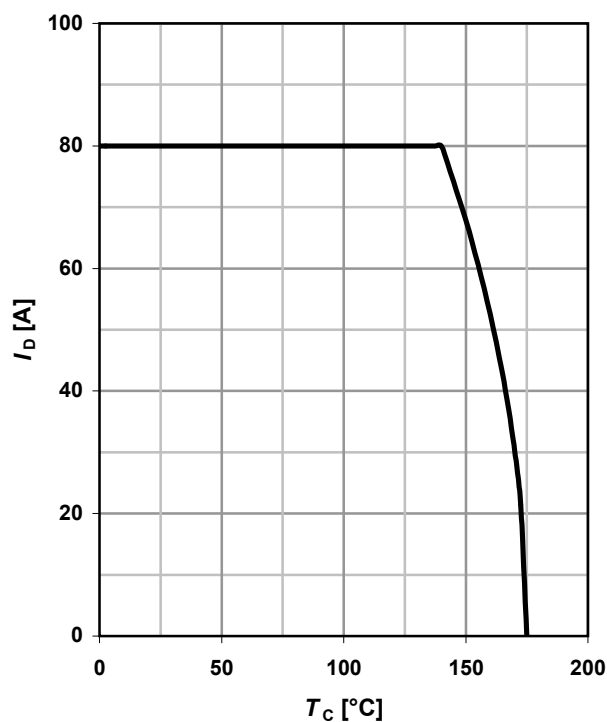
### 1 Power dissipation

$$P_{\text{tot}} = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$



### 2 Drain current

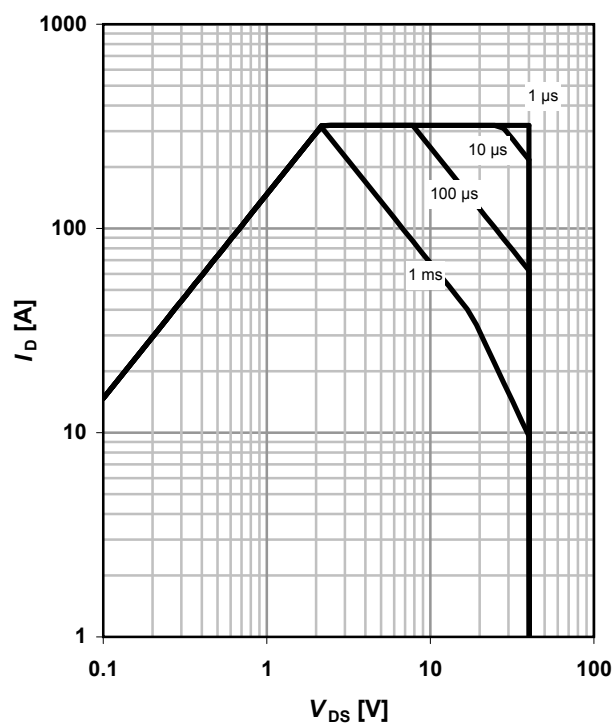
$$I_D = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$



### 3 Safe operating area

$$I_D = f(V_{\text{DS}}); T_C = 25 \text{ °C}; D = 0; \text{SMD}$$

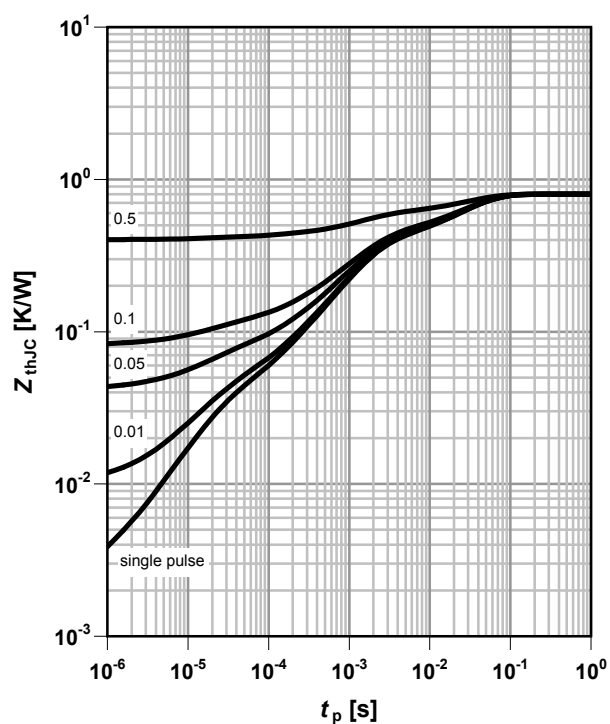
parameter:  $t_p$



### 4 Max. transient thermal impedance

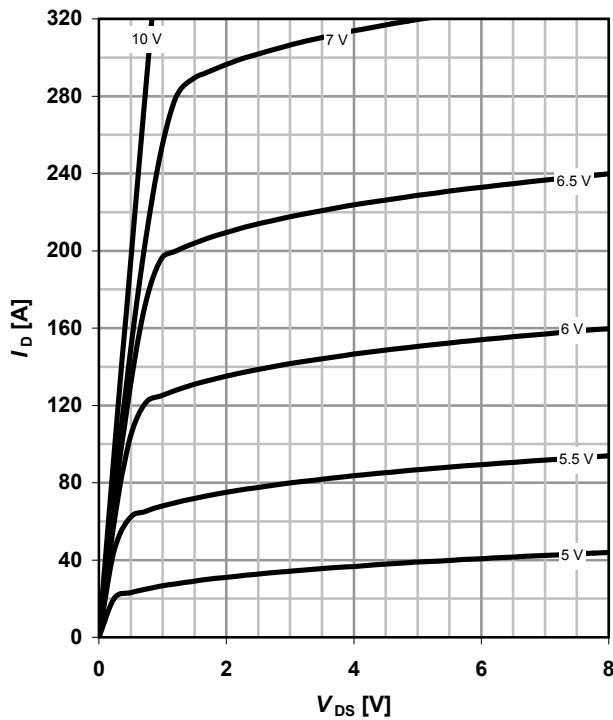
$$Z_{\text{thJC}} = f(t_p)$$

parameter:  $D = t_p/T$



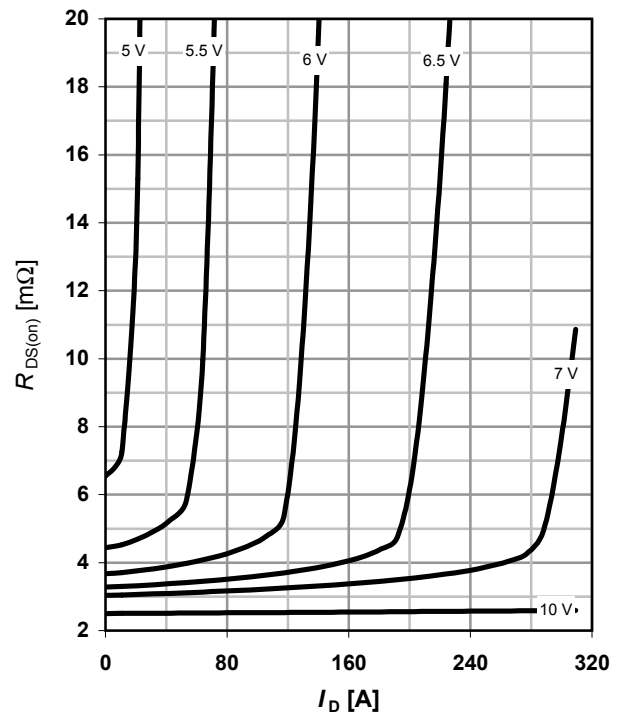
## 5 Typ. output characteristics

 $I_D = f(V_{DS}); T_j = 25^\circ\text{C}; \text{SMD}$ 

parameter:  $V_{GS}$ 


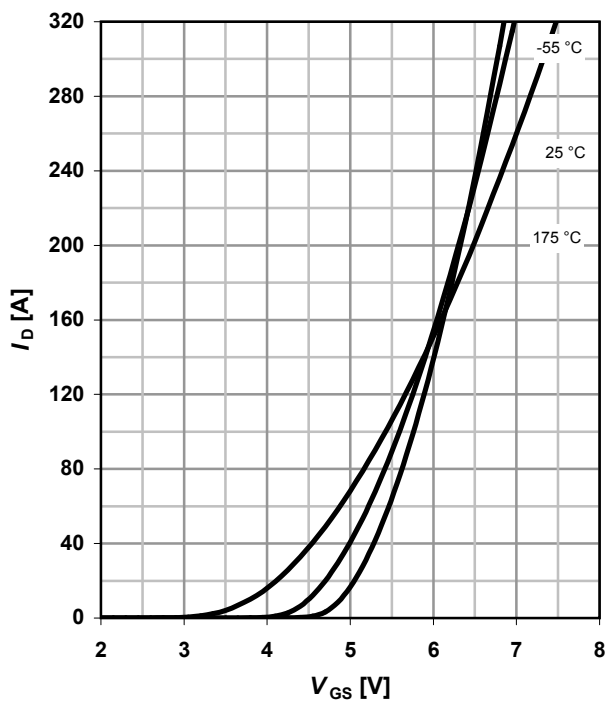
## 6 Typ. drain-source on-state resistance

 $R_{DS(on)} = f(I_D); T_j = 25^\circ\text{C}; \text{SMD}$ 

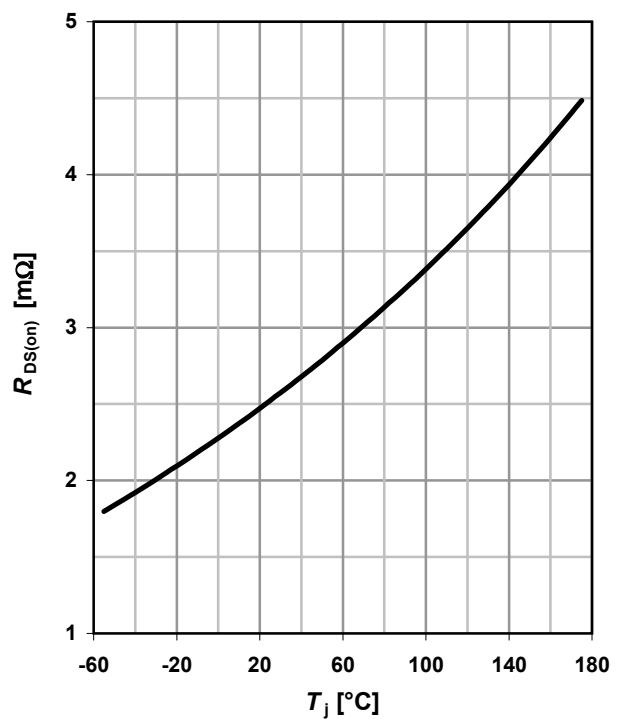
parameter:  $V_{GS}$ 


## 7 Typ. transfer characteristics

 $I_D = f(V_{GS}); V_{DS} = 6\text{V}$ 

parameter:  $T_j$ 


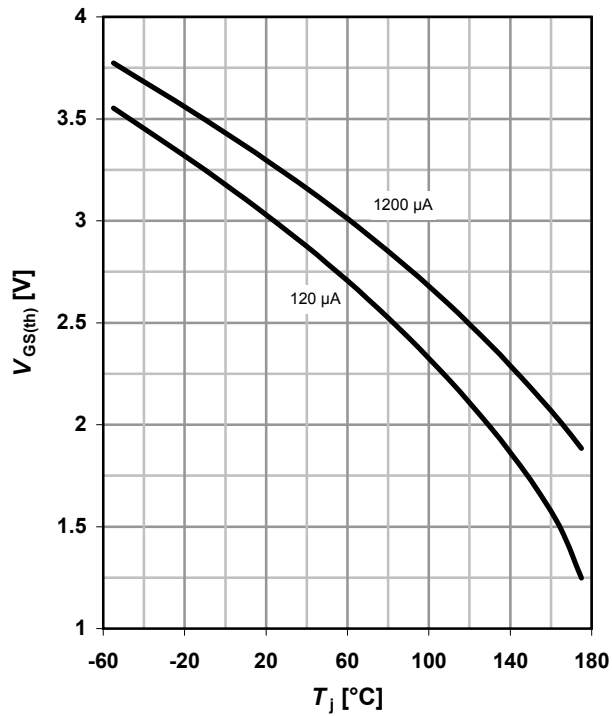
## 8 Typ. drain-source on-state resistance

 $R_{DS(on)} = f(T_j); I_D = 80\text{ A}; V_{GS} = 10\text{ V}; \text{SMD}$ 


## 9 Typ. gate threshold voltage

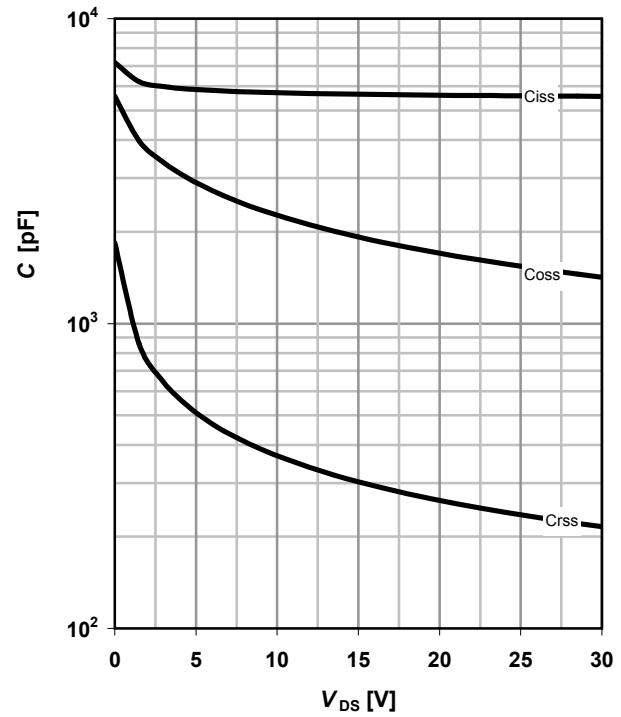
$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$$

parameter:  $I_D$



## 10 Typ. capacitances

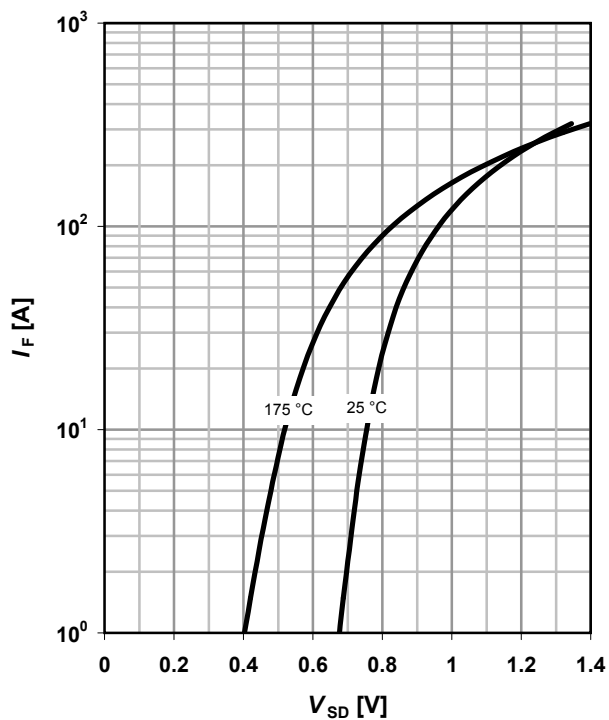
$$C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$$



## 11 Typical forward diode characteristics

$$I_F = f(V_{SD})$$

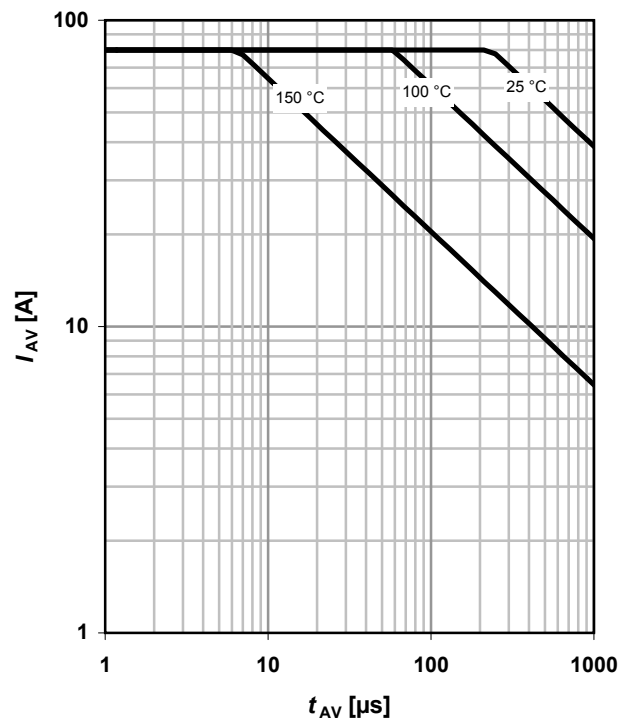
parameter:  $T_j$



## 12 Typ. avalanche characteristics

$$I_{AS} = f(t_{AV})$$

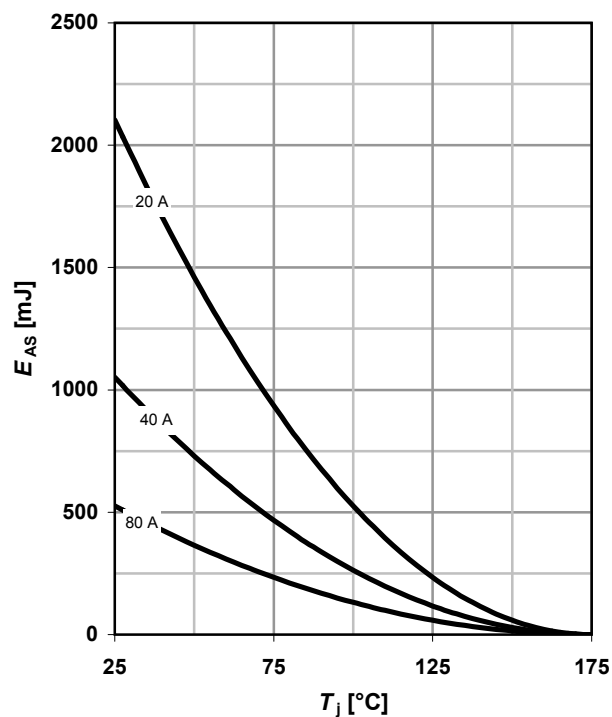
parameter:  $T_{j(start)}$



### 13 Typical avalanche energy

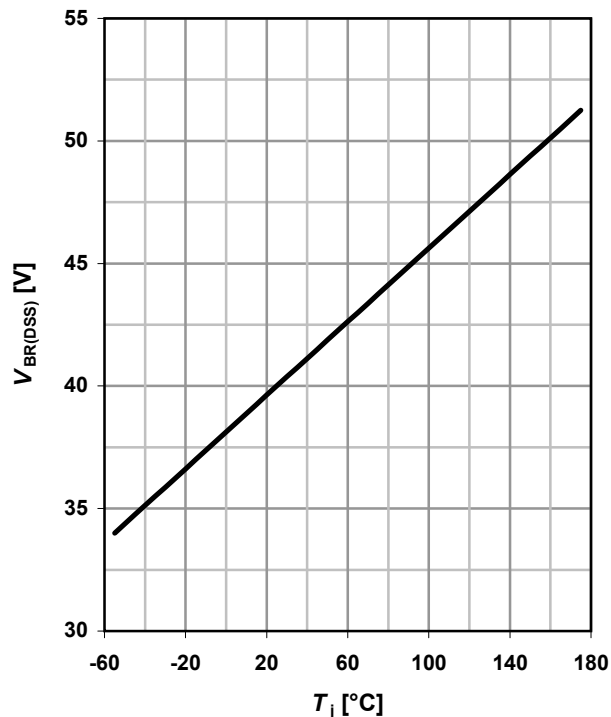
$$E_{AS} = f(T_j)$$

parameter:  $I_D$



### 14 Typ. drain-source breakdown voltage

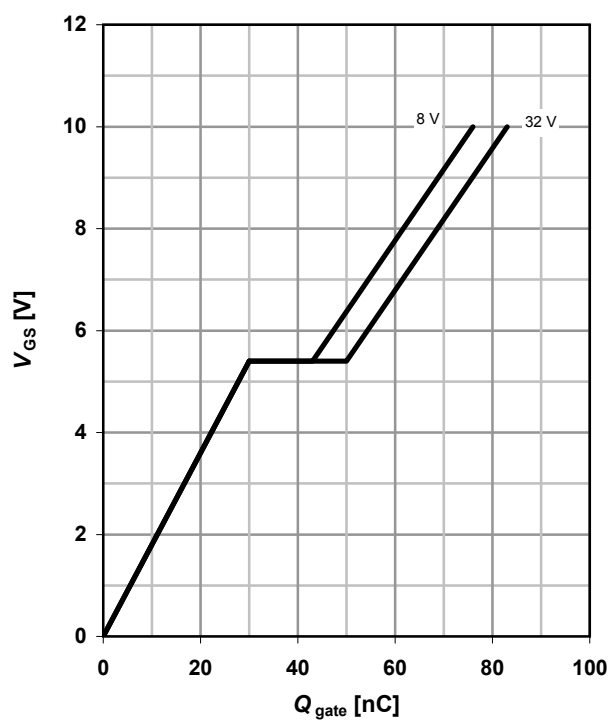
$$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$$



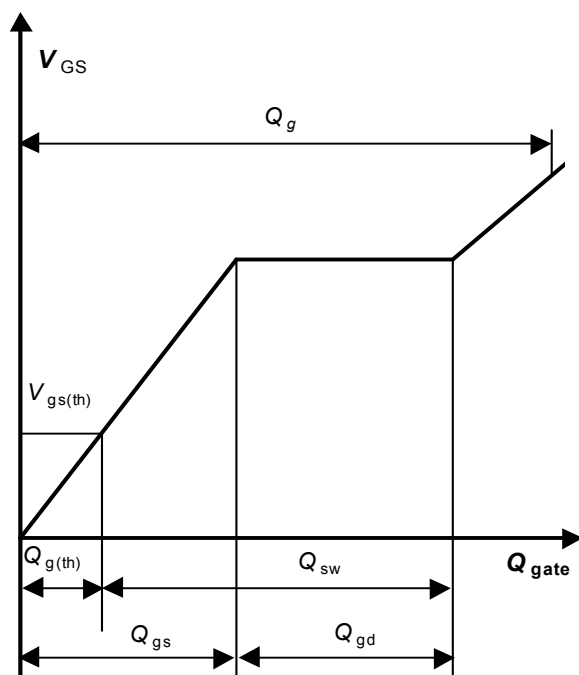
### 15 Typ. gate charge

$$V_{GS} = f(Q_{gate}); I_D = 80 \text{ A pulsed}$$

parameter:  $V_{DD}$



### 16 Gate charge waveforms



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## Revision History

| Version | Date | Changes |
|---------|------|---------|
|         |      |         |
|         |      |         |
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